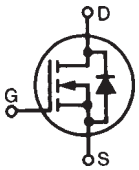
IXYS Preliminary Technical Information

TrenchMV™ Power MOSFET

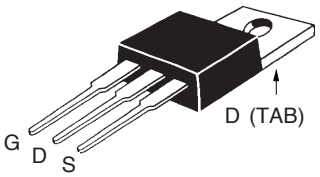
IXTP55N075T
IXTY55N075T

V_{DSS}	=	75	V
I_{D25}	=	55	A
$R_{DS(on)}$	≤	19.5	mΩ

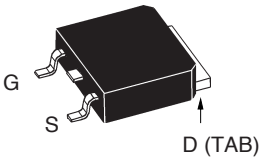
N-Channel Enhancement Mode
Avalanche Rated



TO-220 (IXTP)



TO-252 (IXTY)



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	75	V
V_{DGR}	T_J = 25°C to 175°C; R_{GS} = 1 MΩ	75	V
V_{GSM}	Transient	± 20	V
I_{D25}	T_C = 25°C	55	A
I_L	Package Current Limit, RMS TO-252	25	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	150	A
I_{AR}	T_C = 25°C	10	A
E_{AS}	T_C = 25°C	250	mJ
dv/dt	$I_S \le I_{DM}$, di/dt ≤ 100 A/μs, $V_{DD} \le V_{DSS}$ $T_J \le$ 175°C, R_G =18 Ω	3	V/ns
P_D	T_C = 25°C	130	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	1.6 mm (0.062 in.) from case for 10 s	300	°C
T_{SOLD}	Plastic body for 10 seconds	260	°C
M_d	Mounting torque (TO-220)	1.13 / 10	Nm/lb.in.
Weight	TO-220	3	g
	TO-252	0.35	g

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0 V, I_D = 250 μA	75			V
$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 25 μA	2.0		4.0	V
I_{GSS}	V_{GS} = ± 20 V, V_{DS} = 0 V			± 100	nA
I_{DSS}	V_{DS} = V_{DSS}			1	μA
	V_{GS} = 0 V T_J = 150°C			100	μA
$R_{DS(on)}$	V_{GS} = 10 V, I_D = 0.5 I_{D25}, Notes 1, 2			19.5	mΩ

Features
- Ultra-low On Resistance
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect
- 175 °C Operating Temperature

Advantages
- Easy to mount
- Space savings
- High power density

Applications
- Automotive
  - Motor Drives
  - 42V Power Bus
  - ABS Systems
- DC/DC Converters and Off-line UPS
- Primary Switch for 24V and 48V Systems
- High Current Switching Applications

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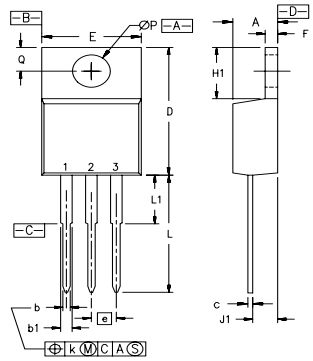
Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS}= 10 V; I_D = 0.5 I_{D25}, Note 1	16	27		S
C_{iss}			1400		pF
C_{oss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		235		pF
C_{rss}			123		pF
$t_{d(on)}$			20		ns
t_r	V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 10 A		50		ns
$t_{d(off)}$	R_G = 18 Ω (External)		44		ns
t_f			41		ns
$Q_{g(on)}$			33		nC
Q_{gs}	V_{GS}= 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 10 A		10		nC
Q_{gd}			9		nC
R_{thJC}				1.15	°C/W
R_{thCS}	TO-220		0.5		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0 V			55	A
I_{SM}	Repetitive			150	A
V_{SD}	I_F = 25 A, V_{GS} = 0 V, Note 1			1.2	V
t_{rr}	I_F = 25 A, -di/dt = 100 A/µs V_R = 40 V, V_{GS} = 0 V		50		ns

TO-220 (IXTP) Outline

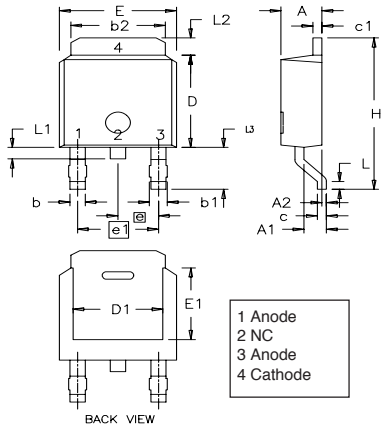


Pins: 1 - Gate 2 - Drain
3 - Source 4, TAB - Drain

SYM	INCHES MIN	MAX	MILLIMETERS MIN	MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

Notes:
1. Pulse test: t ≤ 300 µs, duty cycle d ≤ 2 %;
2. On through-hole packages, $R_{DS(on)}$ Kelvin test contact location must be 5 mm or less from the package body.

TO-252 (IXTY) Outline



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	2.19	2.38	0.086	0.094
A1	0.89	1.14	0.035	0.045
A2	0	0.13	0	0.005
b	0.64	0.89	0.025	0.035
b1	0.76	1.14	0.030	0.045
b2	5.21	5.46	0.205	0.215
c	0.46	0.58	0.018	0.023
c1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
D1	4.32	5.21	0.170	0.205
E	6.35	6.73	0.250	0.265
E1	4.32	5.21	0.170	0.205
e	2.28 BSC		0.090 BSC	
e1	4.57 BSC		0.180 BSC	
H	9.40	10.42	0.370	0.410
L	0.51	1.02	0.020	0.040
L1	0.64	1.02	0.025	0.040
L2	0.89	1.27	0.035	0.050
L3	2.54	2.92	0.100	0.115

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6771478 B2 7,071,537

Fig. 1. Output Characteristics @ 25ºC

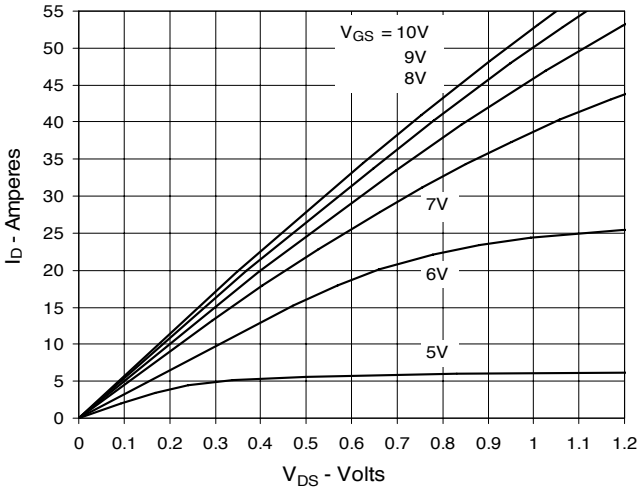

Fig. 2. Extended Output Characteristics @ 25ºC

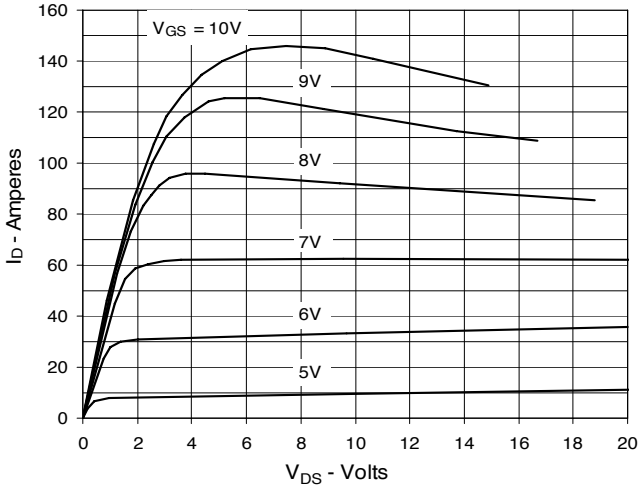

Fig. 3. Output Characteristics @ 150ºC

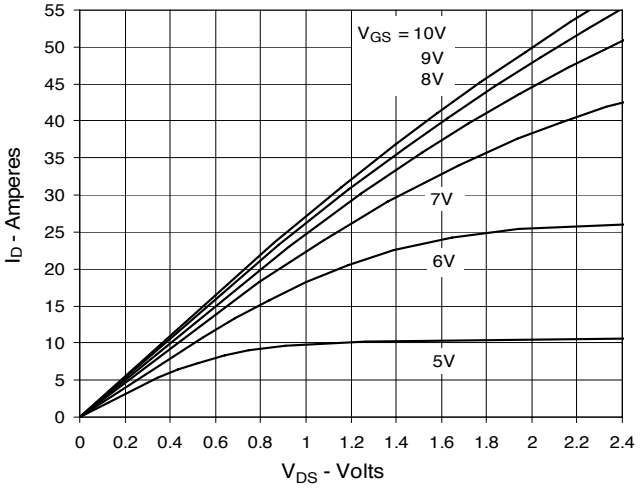

Fig. 4. $R_{DS(on)}$ Normalized to I_D = 27.5A Value vs. Junction Temperature

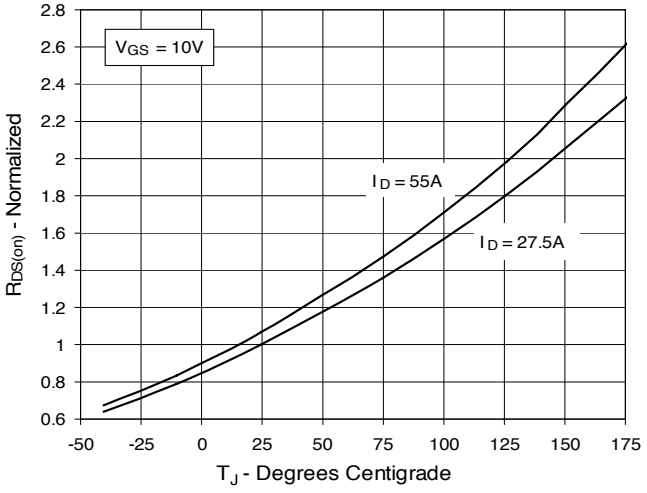

Fig. 5. $R_{DS(on)}$ Normalized to I_D = 27.5A Value vs. Drain Current

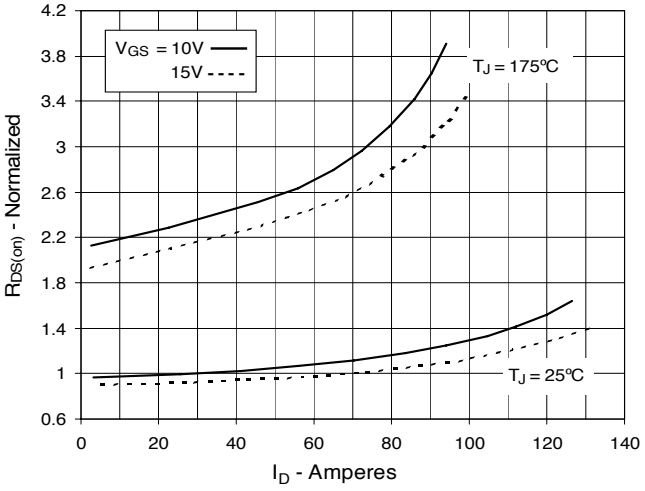

Fig. 6. Maximum Drain Current vs. Case Temperature

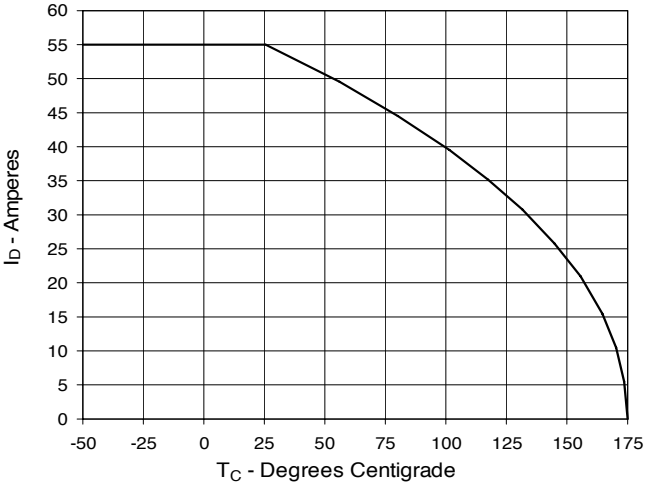

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Fig. 7. Input Admittance

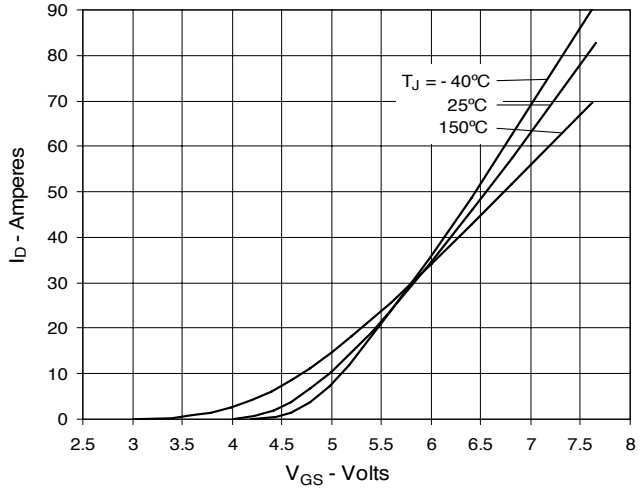


Fig. 8. Transconductance

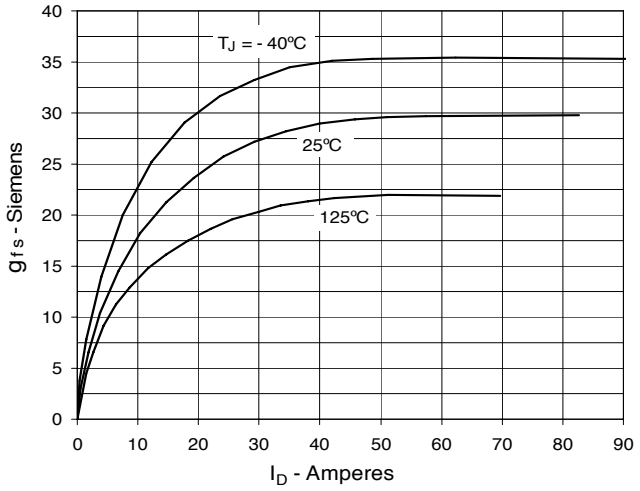


Fig. 9. Forward Voltage Drop of Intrinsic Diode

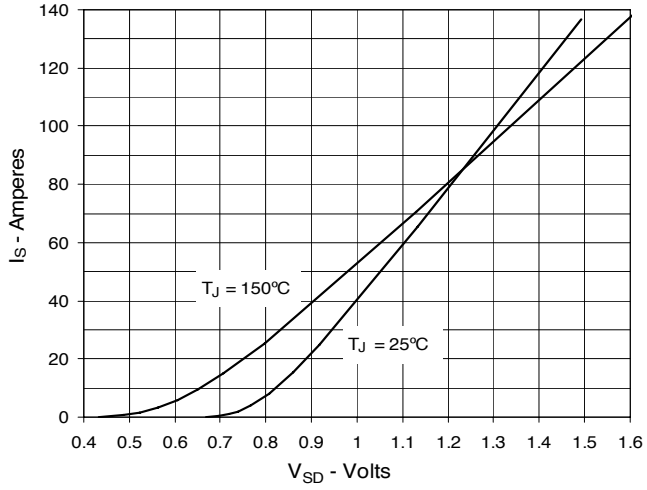


Fig. 10. Gate Charge

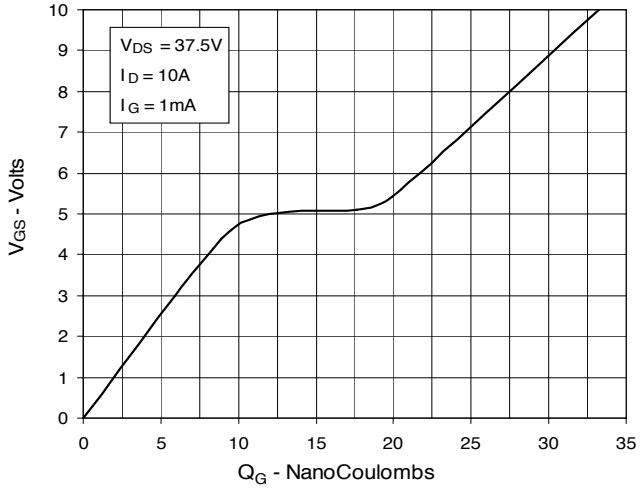


Fig. 11. Capacitance

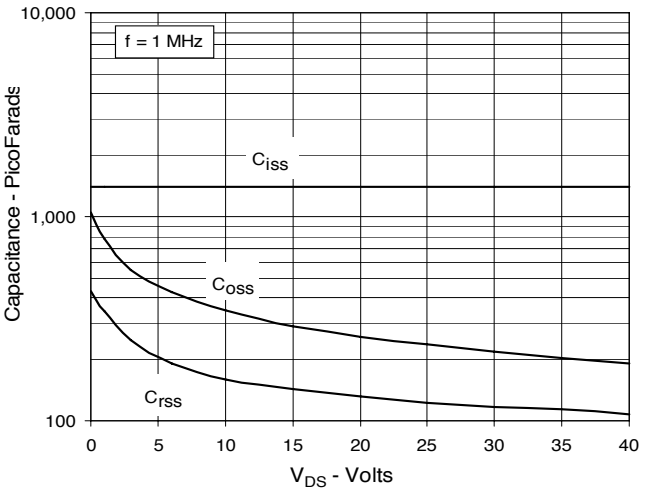
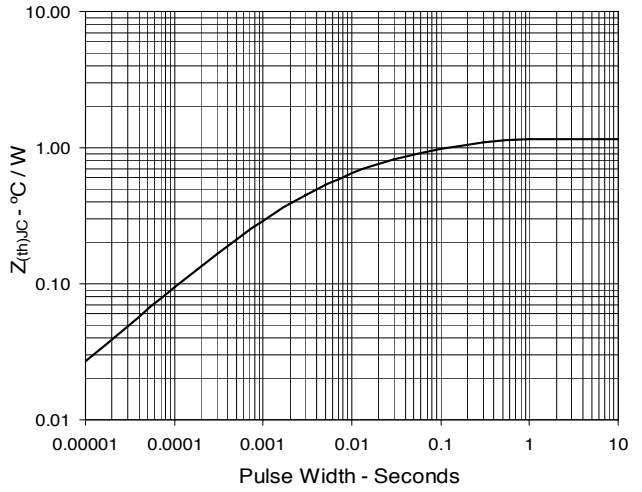


Fig. 12. Maximum Transient Thermal Impedance



IXYS reserves the right to change limits, test conditions, and dimensions.

Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

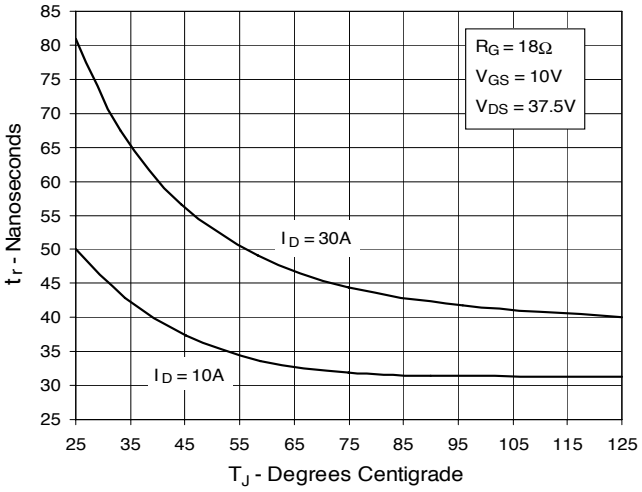


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

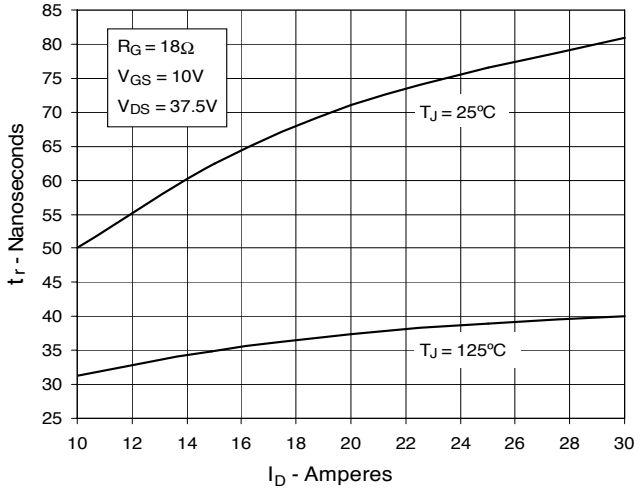


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

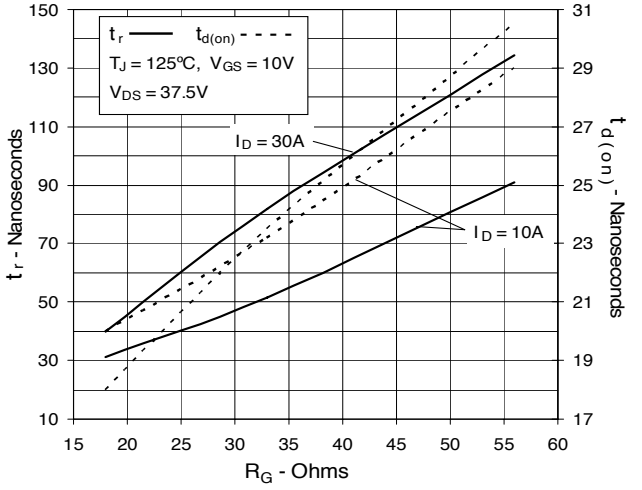


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

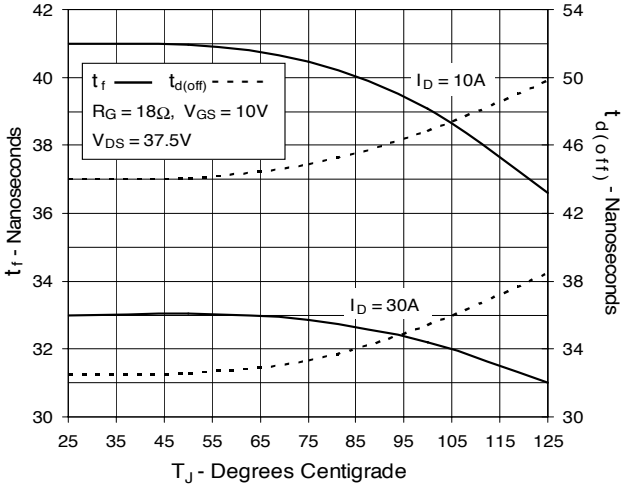


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

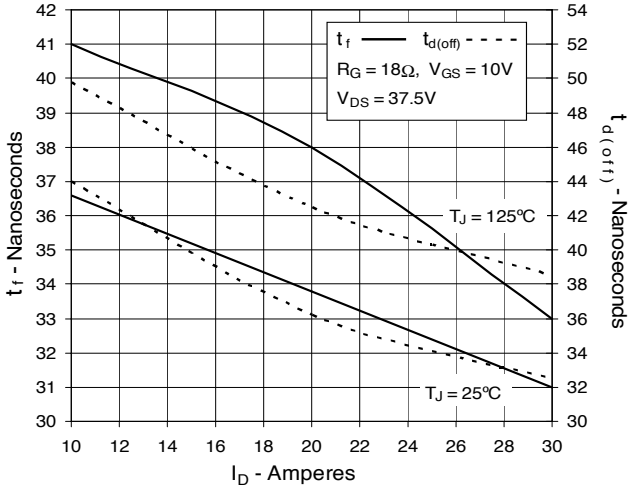
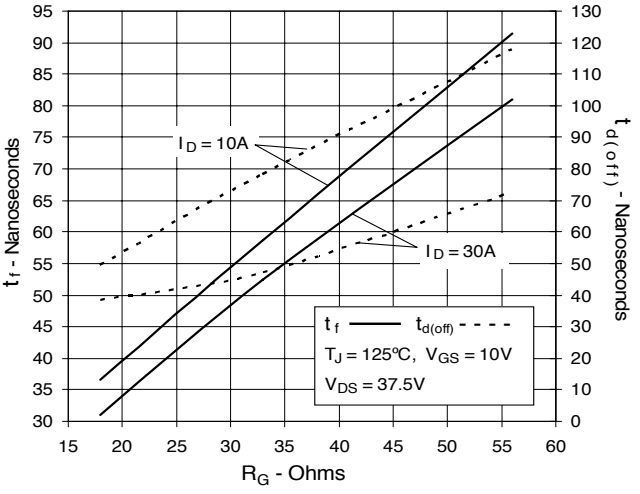


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance



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